

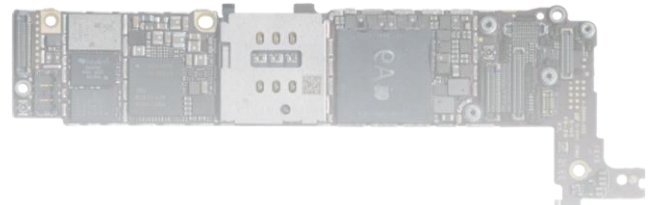
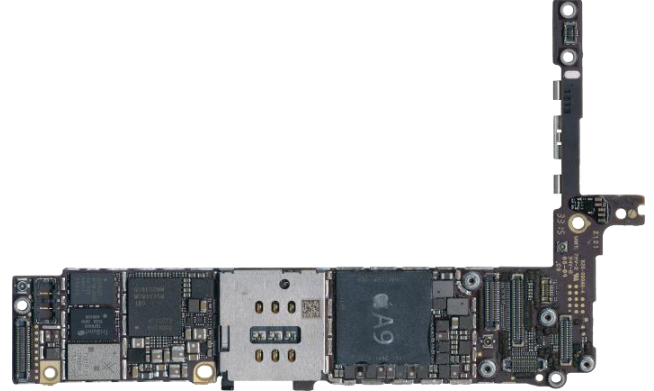
# Apple iPhone 6s plus A1699

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# Teardown Analysis Report

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